

# 2022 IWIPP

Grenoble, France | August 24-26

## International Workshop on Integrated Power Packaging 2022

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Industry Partners .....	3
IWIPP 2022 Leadership Committees .....	4
Media Partner Information .....	5
Welcome from the General Chair .....	6
Welcome from the Technical Chair .....	7
Schedule at a Glance .....	8-9
Keynote Session Description .....	10-11
Oral Presentation Schedule .....	12-16
Sponsoring Society Information .....	17-19
Event Information .....	20-21
Conference Venue Region and Parking Maps .....	22-23
Conference Venue Interior Map .....	24

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SILVER PARTNERS



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EXHIBITORS



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**Francesco Iannuzzo**, AAU Energy,  
Aalborg University, Denmark

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**Nicholas (Nick) Baker**, The University  
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**FINANCIAL CHAIR**

**Andrew (Andy) Lemmon**, The  
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**Brian Narveson**, Power Sources  
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**PUBLICATIONS CHAIR**

**Ramchandra (Ram) Kotecha**, General  
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**Pierre-Olivier Jeannin**, G2ELab,  
France

**Jean-Luc Schanen**, G2ELab, France

**TECHNICAL PROGRAM COMMITTEE**

**Eckart Hoene**, Fraunhofer IZM,  
Germany

**Stefan Mollov**, Infineon Technologies,  
Germany

**Peter Friedrichs**, Infineon  
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**Mona Ghassemi**, The University of  
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**John Bultitude**, KEMET Electronics  
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**Cyril Buttay**, CNRS - Laboratoire  
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**Patrick McCluskey**, University of  
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**Ramchandra Kotecha**, General  
Electric, USA

**Andrew Lemmon**, The University of  
Alabama, USA

SPECIAL THANKS TO IWIPP's 2022 MEDIA PARTNER  
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On behalf of the organizing committee, it is my great pleasure to welcome you to Grenoble, France for the 5<sup>th</sup> IEEE International Workshop on Integrated Power Packaging (IWIPP 2022). IWIPP's mission is to get academics and industrial experts from all over the world who are active in the field of packaging and related topics in contact with each other and foster high-level networking and collaboration opportunities. IWIPP is technically sponsored by the IEEE Power Electronics Society (PELS), Electronics Packaging Society (EPS), and Dielectrics and Electrical Insulation Society (DEIS), as well as Power Sources Manufacturers Association (PSMA) and the European Center for Power Electronics (ECPE). Not least, we can proudly state that IWIPP 2022 would not have been possible without the convinced financial partnership of our silver partners Nanowired and Pink, and our exhibitors PVATePla and Wolfspeed.

The technical committee has built a very exciting program assembling several keynote lecturers from all over the world, thus taking the workshop to a high-level profile in the packaging sector. Worth mentioning, IWIPP 2022 will be held in a hybrid form, in such a way to let experts from countries with travel restrictions as well attend the workshop. We are confident that the hybrid experience will run easily and smoothly, letting remote attendees have a comfortable and enjoyable experience.

Grenoble is the headquarter of G2Elab, which is a world-leading laboratory in the field of innovative packaging solutions for next-generation power electronics applications. A visit to the G2Elab premises will be arranged on the second day.

*Grenoble's history goes back over 2,000 years, to a time when it was a village of the Allobroges Gallic tribe. It has been a parliamentary and military city, close to the border with Savoy when this was yet part of the Holy Roman Empire. Industrial development increased the prominence of Grenoble through several periods of economic expansion over the last three centuries. This started with a booming glove industry in the 18<sup>th</sup> and the 19<sup>th</sup> century, continued with the development of a strong hydropower industry in the late 19<sup>th</sup> to the early 20<sup>th</sup> century, and ended with a post-World War II economic boom symbolized by the 10<sup>th</sup> Olympic Winter Games held in Grenoble in 1968. The city has grown to be one of Europe's most important research, technology, and innovation centers, with one in five inhabitants working directly in these fields. The city holds the title of European Green Capital in 2022. [Wikipedia]*

I believe that all the ingredients are in place for an exciting and profitable IWIPP workshop on August 24, 25, and 26. I wish you a pleasant and fruitful event and I look forward to seeing you in Grenoble!

Francesco Iannuzzo, Ph.D.

General chair





The Technical Committee members and I are excited to present the IWIPP 2022 program.

According to the current megatrends, power converters such as the ones enabling electric vehicles, electric aircraft, rail, smart grid, and renewable energy require new solutions for higher performance and reliability. New-concept power electronic modules are by nature the core part of such solutions. However, they bring along several challenges in terms of low-inductance interconnections, new insulating materials, and reduced electromagnetic interference (EMI). All the above topics as well as reliability issues are the traditional focus of the IWIPP workshop. This year, we can count on a rich program founding mainly on the above three pillars.



IWIPP is unique from other conferences and workshops in the sense that it demands expertise from electrical engineering, mechanical engineering, thermal engineering, physics, and material science to address the large variety of multi-disciplinary challenges in power packaging. In addition, a collection of first technical institutions sponsoring the event (IEEE DEIS, EPS, and PELS, PSMA, and ECPE) as well as a remarkable list of experts on the technical committee makes IWIPP an unmissable appointment for experts active in the field.

This year, IWIPP will welcome keynote speakers on each of the three days that will present challenges and breakthrough technologies consisting of novel die interconnections, insulation challenges, environmental tests, reliability trends, and electromagnetic interference. We have reserved several possibilities for discussion and networking throughout the entire three-day span of the workshop, bearing in our minds the importance of interacting among peers. Keynote sessions will kick off all six half-days as initiators and a stimulus for the following technical discussions.

In addition to the oral sessions, there will be an exciting poster session held in the exhibition area, which will give a great opportunity for fruitful interaction. It is worth to be noted that the workshop will be held in a hybrid form to let interested people participate from countries still with travel restrictions. We committed ourselves to making their experience as comfortable and enjoyable as possible.

We are all looking forward to sharing this unique experience with you in Grenoble.

Nicholas (Nick) Baker, Ph.D.

Technical Chair

**WEDNESDAY 24TH AUGUST 2022**

08:30 AM – 08:45 AM	Welcome Comments: Francesco Iannuzzo
08:45 AM – 09:35 AM	<b>Keynote 1: Eckart Hoene, Fraunhofer</b>
09:35 AM – 10:25 AM	<b>Power Modules Session 1</b>
10:25 AM – 10:45 AM	<b>Coffee Break</b>
10:45 AM – 12:00 PM	<b>Power Modules Session 2</b>
12:00 PM – 13:00 PM	<b>Lunch</b>
13:00 PM – 13:50 PM	<b>Keynote 2: Tamara Baksht, VisIC</b>
13:50 PM – 14:40 PM	<b>Manufacturing Processes Session 1</b>
14:40 PM – 15:00 PM	<b>Coffee Break</b>
15:00 PM – 16:15 PM	<b>Manufacturing Processes Session 2</b>
16:15 PM – 17:45 PM	<b>Poster Session and Welcome Reception</b>

**THURSDAY 25TH AUGUST 2022**

08:45 AM – 09:35 AM	<b>Systems Session 1</b>
09:35 AM – 10:25 AM	<b>Diamond Semiconductors Session 1</b>
10:25 AM – 10:45 AM	<b>Coffee Break</b>
10:45 AM – 12:00 PM	<b>Dielectrics/Insulation Session 1</b>
12:00 PM – 13:00 PM	<b>Lunch</b>
13:00 PM – 13:50 PM	<b>Keynote 3: Chris Genthe, Rockwell Automation [Virtual]</b>
13:50 PM – 14:40 PM	<b>Systems Session 2</b>
14:40 PM – 15:00 PM	<b>Coffee Break</b>
15:00 PM – 15:25 PM	<b>Systems Session 3</b>
15:25 PM – 16:15 PM	<b>Keynote 4: Mona Ghassemi, UT Dallas [Virtual]</b>
18:00 PM – 21:00 PM	<b>Lab Tour at G2Elab and Workshop Dinner</b>



**FRIDAY 26TH AUGUST 2022**

08:45 AM – 09:35 AM	<b>Keynote 5: Francesco Iannuzzo, Aalborg University</b>
09:35 AM – 10:25 AM	<b>Thermal and Reliability Session 1</b>
10:25 AM – 10:45 AM	<b>Coffee Break</b>
10:45 AM – 12:00 PM	<b>Thermal and Reliability Session 2</b>
12:00 PM – 13:00 PM	<b>Lunch</b>
13:00 PM – 13:50 PM	<b>Keynote 6: Aaron Brovont, PC Krause [Virtual]</b>
13:50 PM – 15:05 PM	<b>EMI Session 1</b>
15:05 PM – 15:15 PM	Final Remarks: Francesco Iannuzzo
15:15 PM	<b>End of Workshop</b>

**REGISTRATION IS OPEN DAILY FROM 7:30 AM TO THE END OF THE TECHNICAL SESSIONS.**

**WORKSHOP LOCATIONS:**

**MAKALU:** Technical Sessions (**Keynotes**, Presentations)

**KILIMANDJARO:** Coffee Breaks, Lunch and Poster Session

**G2Elab: Dinner**

**KEYNOTE 1****PACKAGING, INTEGRATION AND FAST SWITCHING: WHAT HAS BEEN ACHIEVED AND WHAT'S NEXT?**

DR. ECKART HOENE

CHIEF EXPERT POWER ELECTRONICS, FRAUNHOFER IZM,  
GERMANY

*WEDNESDAY 24TH AUGUST 08:45AM – 09:35 AM*

**KEYNOTE 2****THE WAY TO AUTOMOTIVE GAN: THE IMPORTANCE OF PACKAGING**

DR. TAMARA BAKSHT

CEO, VISIC, ISRAEL

*WEDNESDAY 24TH AUGUST 13:00 PM – 13:50 PM*

**KEYNOTE 3****ENVIRONMENTAL TRENDS AND CHALLENGES ON POWER PACKAGING**

CHRIS GENTHE

SENIOR PRINCIPAL ENGINEER, ROCKWELL AUTOMATION

*THURSDAY 25TH AUGUST 13:00 PM - 13:50 PM [\[VIRTUAL\]](#)*

**KEYNOTE 4****INSULATION MATERIALS AND SYSTEMS  
FOR POWER MODULES: CHALLENGES  
AND FUTURE**

DR. MONA GHASSEMI

ASSOCIATE PROFESSOR, UT DALLAS

THURSDAY 26TH AUGUST 15:25 PM - 16:15 PM **[VIRTUAL]**

**KEYNOTE 5****RELIABILITY TRENDS IN POWER  
ELECTRONICS**

PROF. FRANCESCO IANNUZZO

PROFESSOR, AALBORG UNIVERSITY

FRIDAY 26TH AUGUST 08:45 AM - 09:35 AM

**KEYNOTE 6****MODELING AND SIMULATION OF  
CONDUCTED EMI IN POWER ELECTRONIC  
SYSTEMS**

DR. AARON BROVONT

ENGINEER, PC KRAUSE & ASSOCIATES

FRIDAY 26TH AUGUST 13:00 PM - 13:50 PM **[VIRTUAL]**



## Power Modules

**Wednesday 24th August 08:45 AM — 12:00 PM**

Session Chair: Francesco Iannuzzo (Aalborg Univ., Denmark)

08:45 AM	<b>KEYNOTE 1: Packaging, Integration and Fast switching: what has been achieved and what's next?</b> <u>Eckart Hoene</u> ( <i>Fraunhofer, Germany</i> )
09:35 AM	<b>Design of a Test Package for High Voltage SiC Diodes</b> <u>Arthur Boutry</u> ( <i>SuperGrid Institute, France</i> ), Cyril Buttay, Luong Viêt Phung, Bruno Lefebvre, Eric Vagnon, Dominique Planson
10:00 AM	<b>Protecting Power Semiconductors from H<sub>2</sub>S Gases</b> <i>[Virtual]</i> <u>Bjoern Rentemeister</u> ( <i>Infineon, Germany</i> )
10:25 AM	COFFEE BREAK
10:45 AM	<b>Harmful Gas Requirements for Power Electronics</b> <i>[Virtual]</i> <u>Victoria Zimmerman</u> ( <i>Fraunhofer, Germany</i> )
11:10 AM	<b>Modular and Double-Sided Air-Cooled Power Module with Paralleled Switching Cells</b> <u>Yvan Avenas</u> ( <i>G2Elab, France</i> )
11:35 AM	<b>Modeling Approach for Design Selection and Reliability Analysis of SiC Power Modules</b> <u>Ivana Kovacevic-Badstuebner</u> ( <i>ETH Zurich, Switzerland</i> ), Salvatore Race, Ulrike Grossner
12:00 PM	LUNCH

## Manufacturing Processes

**Wednesday 24th August 13:50 PM — 16:15 PM**

Session Chair: Nick Baker (Univ. of Alabama, USA)

13:00 PM	<b>KEYNOTE 2: Paving the Way to Automotive GaN: The Importance of Packaging</b> <u>Tamara Baksht</u> ( <i>VisiC, Israel</i> )
13:50 PM	<b>Insights into the Layout of Power Semiconductor Chips</b> <u>Peter Friedrichs</u> ( <i>Infineon, Germany</i> )
14:15 PM	<b>Non-CMOS Compatible SiC Power Device Fabrication in Volume Si Fabs</b> <u>Victor Veliadis</u> ( <i>NCSU, USA</i> )
14:40 PM	COFFEE BREAK
15:00 PM	<b>Thermomechanical Analysis of Si-Chip Fracture Caused by Double-Sided Ag Sintering for PCB Packages</b> <i>[Virtual]</i> <u>Ankit Bhushan Sharma</u> ( <i>Hochschule Kempten, Germany</i> ), Till Huesgen
15:25 PM	<b>Process Advantages of Thermosonic Wedge Bonding Using Dosed Tool Heating</b> <u>Michael McKeown</u> , ( <i>Hesse Mechatronics, USA</i> )
15:50 PM	<b>Usage of NanoWires in Power Modules and Frequency Converters</b> <u>Olav Birlem</u> ( <i>NanoWired GmbH, Germany</i> )
16:15 PM	POSTER SESSION AND WELCOME RECEPTION

## POSTER SESSION and WELCOME RECEPTION

**Wednesday 24th August 16:15 PM — 17:45 PM**

Session Chair: Andrew Lemmon (Univ. of Alabama, USA)

**1. Cu-Sintering for Highly Reliable Interconnects**

Hans-Jürgen Albrecht (*Budatec GmbH, Germany*), Dirk Buße, Alexander Dahlbüdding, A. Hutzler, O. Rämer [\[Virtual\]](#)

**2. Investigation of Space Charge Accumulation Formed in an Insulating Layer of Motor Windings by Voltage Application Through Air Gap**

Shunya Tanaka (*Tokyo City University, Japan*), Kazuki Endo, Kaito Adachihara, Hiroaki Miyake, Yasuhiro Tanaka

**3. Liquid Metal in Power Electronics**

Nick Baker (*Univ. of Alabama, USA*), Szymon Bęczkowski, Francesco Iannuzzo, Andy Lemmon, Su Gupta, Alec Mshar, Asger Jørgensen, Thore Aunsborg, Kjeld Pedersen, Rubén García

**4. Hybrid Variable Frequency Drive with Active Magnetic Bearing for Space Application**

Bela Kagalwala (*Calnetix, USA*), Pana Shenoy

**5. Double Side Cooled Package Based on SiC Trench MOSFETs Enables High Performance for Automotive Drive Train Applications**

Ajay Poonjal Pai (*Infineon, Germany*), Ålex Widhalm, Michael Ebli, Mathias Kurz, Marco La Foresta, Marina Fernández Osorio

**6. An LTSpice – MATLAB Interface for Mitigating Convergence Problems in Circuit Optimization with SPICE [\[Virtual\]](#)**

Pawel Kubulus (*Aalborg University, Denmark*), Asger Bjørn Jørgensen, Szymon Bęczkowski, Stig Munk-Nielsen

**7. Digital Design of 10kV SiC-MOSFET Power Module to Improve Wire-Bonding Layout for Power Cycle Capabilities**

Masaki Takahashi (*Aalborg University, Denmark*), Thore Stig Aunsborg, Christian Uhrenfeldt, Stig Munk-Nielsen, Asger Bjørn Jørgensen

**8. Improved Drain-Source Voltage Detection Method for Short-Circuit Protection of SiC MOSFET [\[Virtual\]](#)**

Qiang Wang (*China University of Mining and Technology, China*), Francesco Iannuzzo, Jingwei Zhang, Yizhan Jiang, Fengyou He



## Systems (Session 1)

**Thursday 24th August 08:45 AM — 09:35 AM**

Session Chair: Jean-Luc Schanen (G2Elab, France)

08:45 AM	<b>A PCB-Based Power Converter for e-Mobility Applications</b> <u>Julien Morand</u> , Johan Le Leslé ( <i>Mitsubishi Electric R&amp;D Centre Europe, France</i> )
09:10 AM	<b>Additively Manufactured Thermally Integrated DC-DC Converter</b> <i>[Virtual]</i> <u>Patrick McCluskey</u> ( <i>University of Maryland, USA</i> )

## Diamond Semiconductors

**Thursday 24th August 09:35 AM — 10:25 AM**

Session Chair: Jean-Luc Schanen (G2Elab, France)

09:35 AM	<b>Diamond Power Devices: Benchmarks, Optimal Design and Integration in Power Converters</b> <u>Nicolas Rouger</u> ( <i>Université de Toulouse, France</i> )
10:00 AM	<b>Thermo-Mechanical Constraints for Packaging of Diamond Components</b> <u>Naüm Fusté</u> , Emma Solà, David Sanchez, Oriol Aviñó, Xavier Perpiñà, Miquel Vellvehí, Xavier Jordà ( <i>CNM Barcelona, Spain</i> )
10:25 AM	COFFEE BREAK

## Dielectrics & Insulation

**Thursday 24th August 10:45 AM — 12:00 PM**

Session Chair: Jean-Luc Schanen (G2Elab, France)

10:45 AM	<b>Electric Field Grading in HV Integrated Systems: State-of-the-Art and Future Prospects</b> <i>[Virtual]</i> <u>Sombel Diahm</u> ( <i>Université de Toulouse, France</i> )
11:10 AM	<b>Advanced Insulation Technology for Electrical and Electronic Equipment</b> <u>Keni Okamoto</u> ( <i>Fuji Electric, Japan</i> )
11:35 AM	<b>High Temperature Dielectric Properties of Aluminum Nitride Substrates with Different Amounts of Titanium</b> <i>[Virtual]</i> <u>Daigo Okumura</u> ( <i>Kyushu Institute of Technology, Japan</i> ), Kyouhei Hamasuna, Masahiro Kozako, Masayuki Hikita, Tomohito Nagami, Kouichi Yamamoto
12:00 PM	LUNCH



## Systems (Session 2)

**Thursday 24th August 13:00 PM — 14:40 PM**

Session Chair: Peter Friedrichs (Infineon, Germany)

13:00 PM	<b>KEYNOTE 3: Environmental Trends and Challenges on Power Packaging</b> <i>[Virtual]</i> <u>Chris Genthe</u> (Rockwell Automation, USA)
13:50 PM	<b>Series Connected SiC MOSFETs Voltage Balancing: Two Methods with Adaptive Delays</b> <u>Cedric Mathieu De Vienne</u> (SuperGrid Institute, France)
14:15 PM	<b>10 kV SiC MOSFET Medium Voltage Modular Converter using Integrated Capacitor-Blocked Transistor (ICBT) Cells</b> <u>Rolando Burgos</u> (Virginia Tech, USA)
14:40 PM	COFFEE BREAK

## Systems (Session 3)

**Thursday 24th August 15:00 PM—16:15 PM**

Session Chair: Eckart Hoene (Fraunhofer, Germany)

15:00 PM	<b>Advanced WBG Module Packaging and EMI Self-containment Design</b> <i>[Virtual]</i> <u>Fang Luo</u> (SUNY, USA)
15:25 PM	<b>KEYNOTE 4: Insulation Materials and Systems for Power Modules: Challenges and Future</b> <i>[Virtual]</i> <u>Mona Ghassemi</u> (UT Dallas, USA)

## Social Event

**Thursday 24th August 18:00 PM — 21:00 PM**

18:00 PM	<b>Tour of G2Elab</b>
19:00 PM	<b><u>Workshop Dinner @ G2Elab</u></b>

## Thermal and Reliability

Friday 26th August 08:45 AM — 12:00 PM

Session Chair: Cyril Buttay (INSA-Lyon, France)

08:45 AM	<b>KEYNOTE 5: Reliability Trends in Power Electronics</b> <u>Francesco Iannuzzo</u> (Aalborg University, Denmark)
09:35 AM	<b>On-Chip Junction Temperature Measurement using FBG Sensors</b> <i>[Virtual]</i> <u>Sinisa Durovic</u> (University of Manchester, UK)
10:00 AM	<b>Mechanical Lifetime Testing of Wire-Bonds and Solder Joints vs. Power Cycling</b> <u>Golta Khatibi</u> (TU Wien, Austria)
10:25 AM	COFFEE BREAK
10:45 AM	<b>Recent Advances in Condition Monitoring for Power Semiconductors</b> <u>Vincent Quemener</u> (Mitsubishi Electric R&D Centre Europe, France)
11:10 AM	<b>Online In-Situ Device Monitoring for Real-time Diagnostics and Prognostics of Power and Circuit Protection Systems</b> <u>Jim Gafford</u> (University of North Carolina, Charlotte, USA)
11:35 AM	<b>A Novel Packaging with Direct Dielectric Liquid Cooling for High Voltage Power Electronics</b> <u>Amin Al-Hinaai</u> (Hochschule Kempten, Germany), Till Huesgen, Cyril Buttay, Eric Vagnon, Richard Zeitler, Daniela Meyer
12:00 PM	LUNCH

## Electromagnetic Interference and Emissions

Friday 26th August 13:00 PM — 15:00 PM

Session Chair: Francesco Iannuzzo (Aalborg University, Denmark)

13:00 PM	<b>KEYNOTE 6: Modeling and Simulation of Conducted EMI in Power Electronic Systems</b> <i>[Virtual]</i> <u>Aaron Brovont</u> (PC Krause & Associates, USA)
13:50 PM	<b>Auxiliary Circuit Design for 10kV SiC MOSFET Modules</b> <i>[Virtual]</i> <u>Jun Wang</u> (University of Nebraska-Lincoln, USA)
14:15 PM	<b>Packaging Design for Low EMI Generation from Power Modules</b> <u>Pierre-Olivier Jeannin</u> (G2Elab, France)
14:40 PM	<b>Comparison of FEA Techniques for Estimation of Module Parasitics</b> <u>Andrew Lemmon</u> (Univ. of Alabama, USA)
15:05 PM	<b>Final Remarks and Workshop Conclusion</b> <u>Francesco Iannuzzo</u> (Aalborg University, Denmark)

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## European Center for Power Electronics (ECPE)

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ECPE, the Industry-driven Power Electronics Research Network in Europe with more than 170 member organizations is promoting research, expert workshops and advanced training as well as public relations in power electronics. The ECPE Network covering the value chain from the materials and components to the systems and applications strengthens the cooperation between Power Electronics industry and university & research institutes on a European level. As a European Technology and Innovation Platform ECPE is driving precompetitive joint research and sets up research & technology roadmaps for a strategic research agenda with future research directions according to the demands of European power electronics industry.

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## IEEE Electronics Packaging Society (EPS)

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The IEEE Electronics Packaging Society is the leading international forum for scientists and engineers engaged in the research, design and development of revolutionary advances in microsystems packaging and manufacturing. Its objectives are scientific, literary, and educational in character. The Society strives for the advancement of the theory and practice of electrical and electronics engineering and of the allied arts and sciences, and the maintenance of a high professional standing among its members and others and with special attention of such aims within

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## IEEE Dielectric & Electrical Insulation Society (DEIS)

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445 Hoes Lane  
Piscataway, NJ 08854, USA  
[www.ieeedeis.org](http://www.ieeedeis.org)

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DEIS' interests lie in materials, measurements, numerical modelling, components, applications and systems pertinent to dielectrics and electrical insulation. These include solids, liquids and gases; small-scale systems such as nano-dielectrics and bio-dielectrics; high-voltage and high-field phenomena; and large-scale systems such as high-power insulation applied to electricity generation, transmission, and distribution. DEIS supports the basic science of dielectrics and electrical insulation through practical applications and the development of relevant standards.

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## IEEE Power Electronics Society (PELS)

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The Power Electronics Society is one of the fastest growing technical societies of IEEE. For over 20 years, PELS has facilitated and guided the development and innovation in power electronics technology. This technology encompasses the effective use of electronic components, the application of circuit theory and design techniques, and the development of analytical tools toward efficient conversion, control and condition of electric power. The Power Electronics Society's goal is to keep members current and competitive in the workplace, and provide them with the tools necessary to help them grow both personally and professionally.

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## Power Sources Manufacturers Association (PSMA)

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P.O. Box 418  
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***The Multinational Power Electronics Association***

The purpose of PSMA is to enhance the stature and reputation of its members and their products, improve their knowledge of technological and other developments related to power sources, and educate the entire electronics industry, plus academia, as well as government and industry agencies as to the importance of, and relevant applications for, all types of power sources and conversion devices.

## REGISTRATION & HELP DESK

The full-conference registration admits one individual to all technical sessions including keynotes and the poster session, the exhibition atrium, and all social / networking events.

Throughout the duration of the conference, the registration desk will remain staffed for the convenience of the participants. Any conference or program questions may be directed to this help desk; when the conference is not in session, please contact a member of the organizing committee with questions.

## BADGES

Badges should be worn at all official functions of the meeting. Badge checkers will be stationed throughout the meeting areas. Only those with technical registrations will be allowed into sessions. If you forget or lose your badge, you may obtain a second badge at the registration desk with proof of registration.

## RECEIPTS

All participants who register online will receive a receipt/confirmation via email. If you need additional paperwork, please contact the event staff, located at the registration desk.

## CONSENT TO USE OF IMAGES

Registration and attendance / participation in IWIPP constitutes an agreement by the registrant for IWIPP's use and distribution (both now and in the future) of the registrant or attendee's image or voice in photographs, videotapes, electronic reproductions and audiotapes of such events and activities. The use of cameras and/or recorders is strictly prohibited during the oral and poster sessions. Limited use is allowed for Exhibitors in their own booth area. Personal photography is allowed at social functions.

## LOST & FOUND

Any lost & found item should be returned to the registration desk, and will be held by the hosting institution if unclaimed before the end of the event.

## INTERNET ACCESS

Complimentary WiFi is available throughout the conference facilities. The Wi-Fi login and password will be provided when you will register. Please notify the front desk if there are any internet issues.



## CONFERENCE LOCATION

The main program for IWIPP 2022 will be held at the following location:

**Centre de congrès - World Trade Center  
5-7 , place Robert Schuman – BP 1521  
38025 Grenoble Cedex 1 France  
tel: +33 (0)4 76 28 28 80**

## LOCAL TRANSPORTATION

Taxis and public transportation is available in Grenoble. The main conference location is close to the train station and a few minutes walk from the bus station:

- Tram line A: “Gares” station
- Tram line B: “Gares” station
- Tram line B: “Palais de justice - Gare” station
- Bus C1 : “Gares” station

If you come from “Gares” station or from the bus station, you must take the path under the train station to reach the conference center.

## PARKING

There is no free parking close to the conference. The closest parking locations are indicated in the next page of this program.

## DISTRIBUTING COMMERCIAL MATERIAL

Distribution of commercial material in the IWIPP meeting and exhibition spaces by people or organizations not sanctioned as a Partner, Sponsor, or Exhibitor is prohibited. IWIPP reserves the right to remove without notice any materials not in compliance with this policy.

## GALA DINNER INFORMATION

The Gala dinner will be held at 7 PM on August 25, 2022. The dinner is hosted by G2Elab at the following address:

**Bât Green-ER  
21 avenue des Martyrs  
38000 Grenoble**



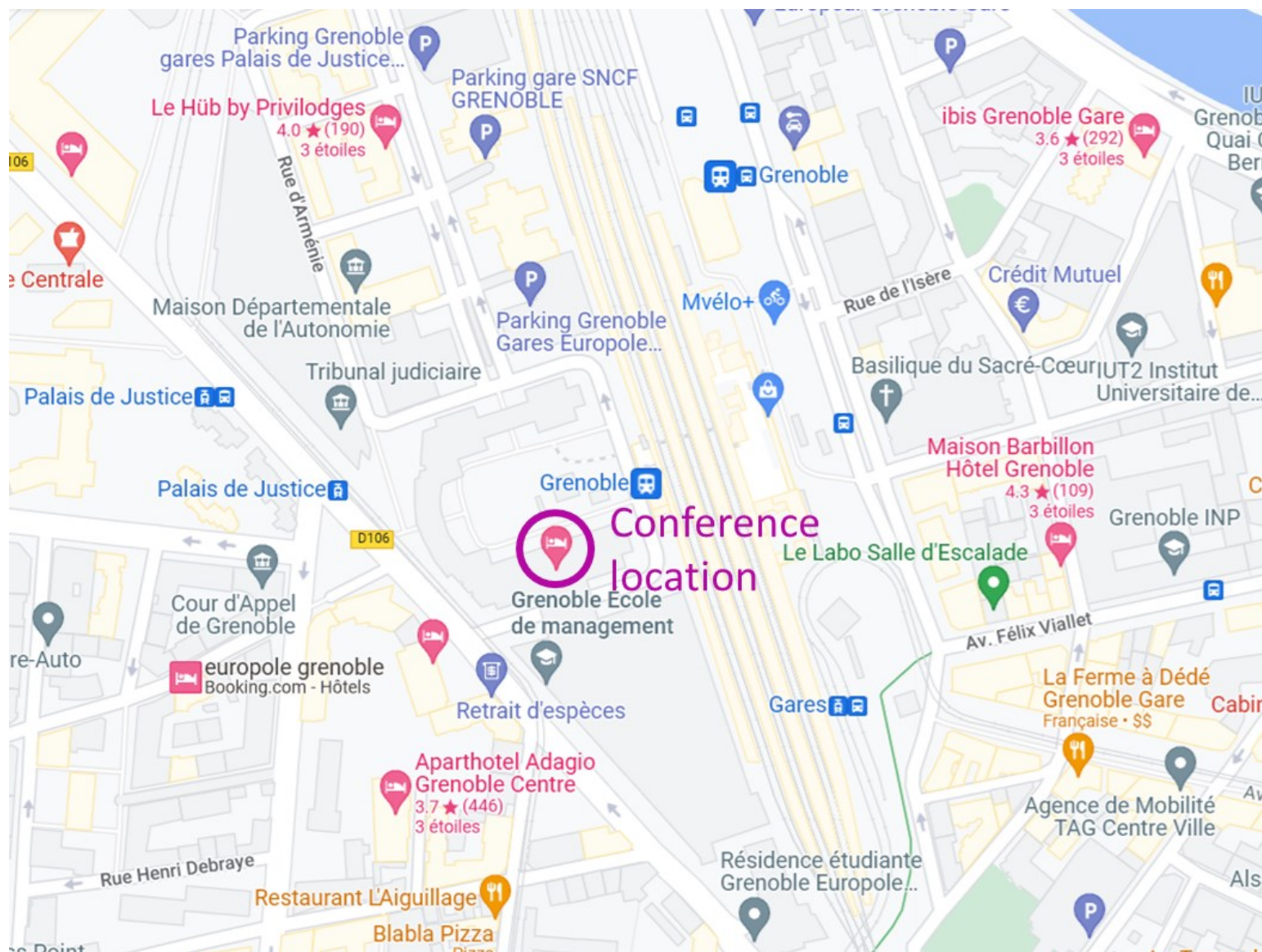
G2Elab can be reached via tram line B at the “Marie-Louise Paris - CEA” station. The Gala Dinner is scheduled to begin at 7 PM at the ground floor in the Forum room. Please take a left after entering the building.

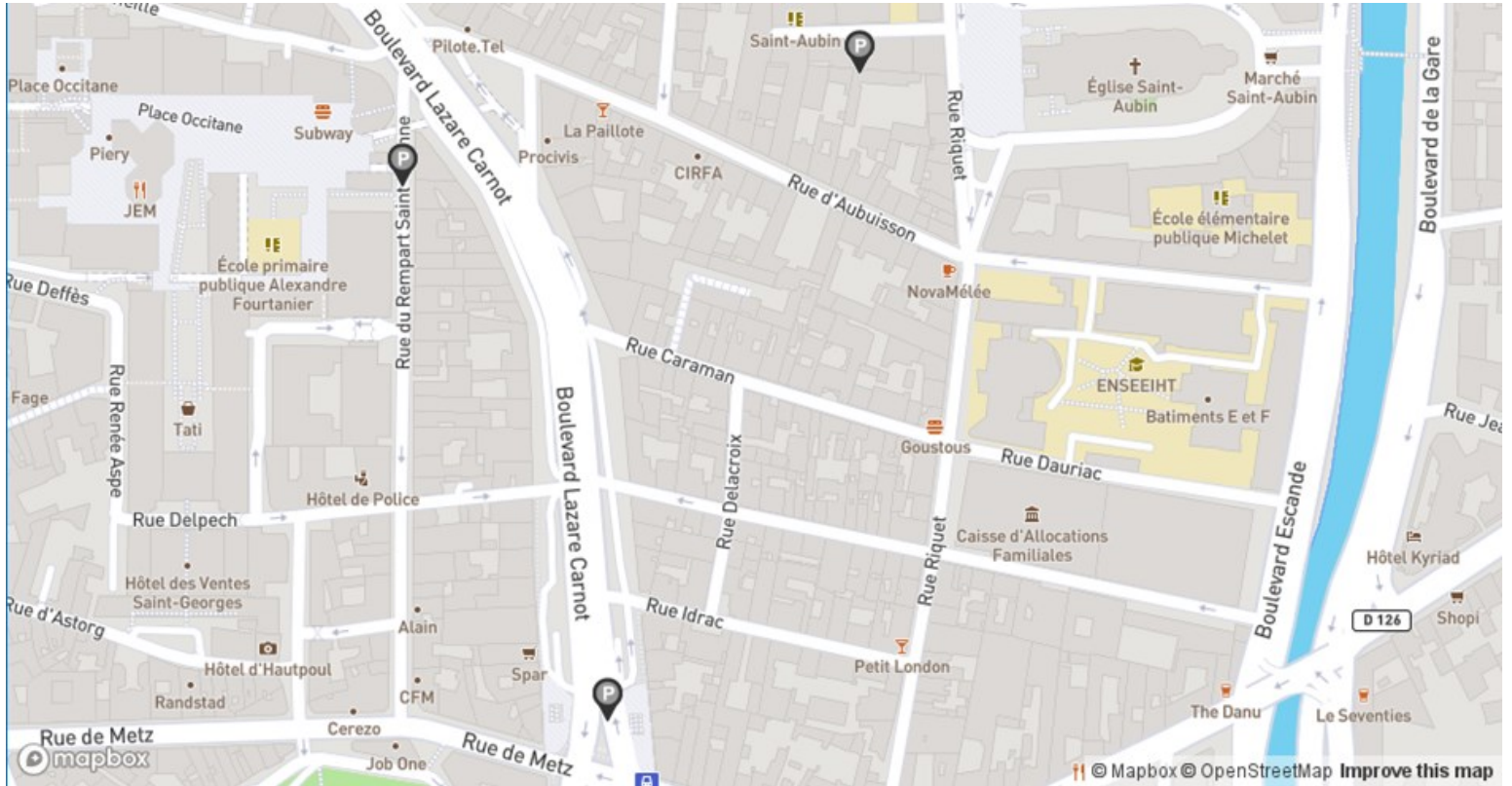
A visit of G2Elab facilities will be provided before the Gala Dinner at 6 PM. We will meet in the main hall at the entrance of the building.

## ACCESSIBILITY FOR REGISTRANTS

The meeting staff will work with attendees to provide reasonable accommodations for those who require special needs. To request assistance on-site, please check in at the Registration & Help Desk.

Also, for local recommendations and additional transportation instructions, please refer to the Conference Location & Local Accommodations pages on the conference website at [www.iwipp.org](http://www.iwipp.org).



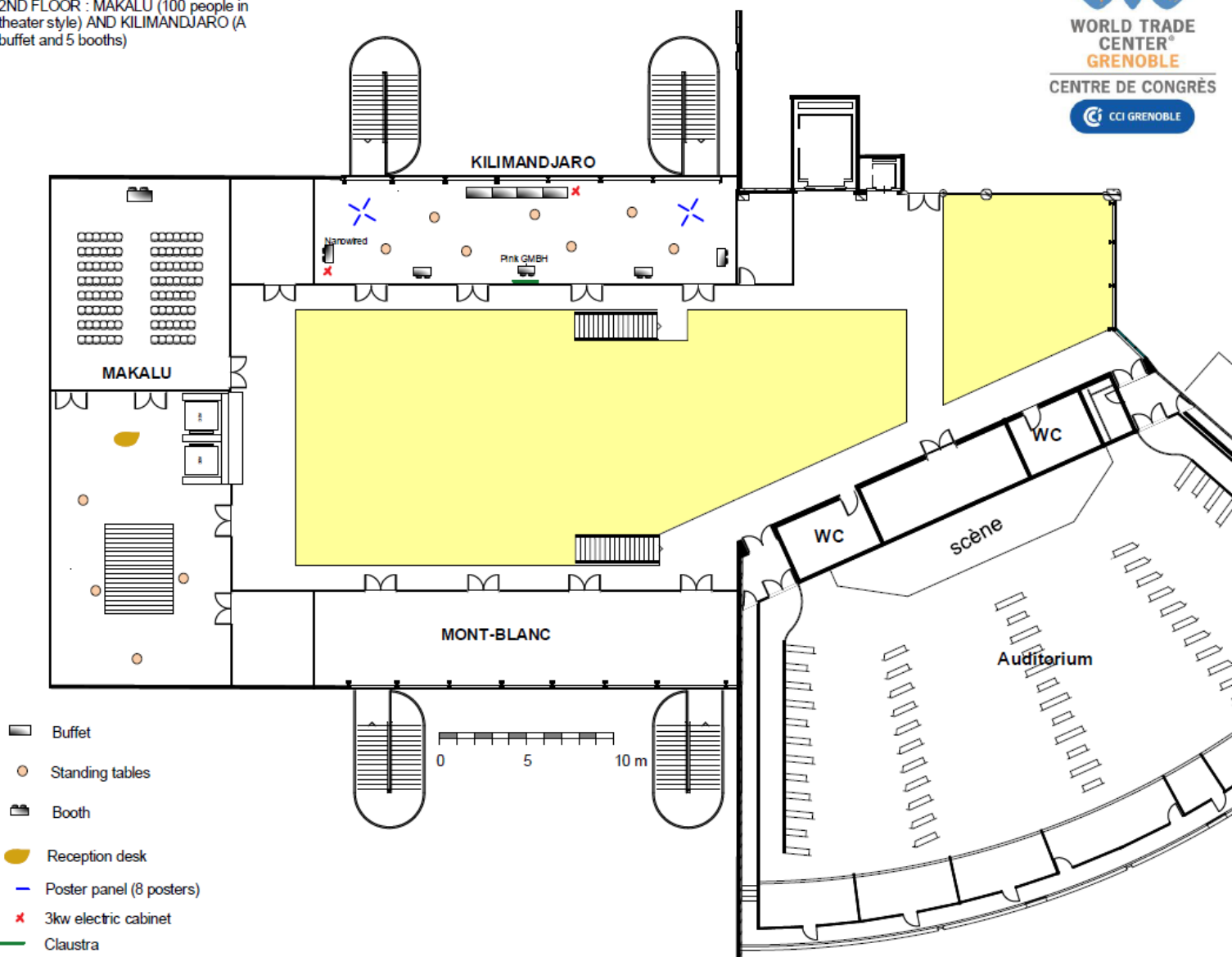


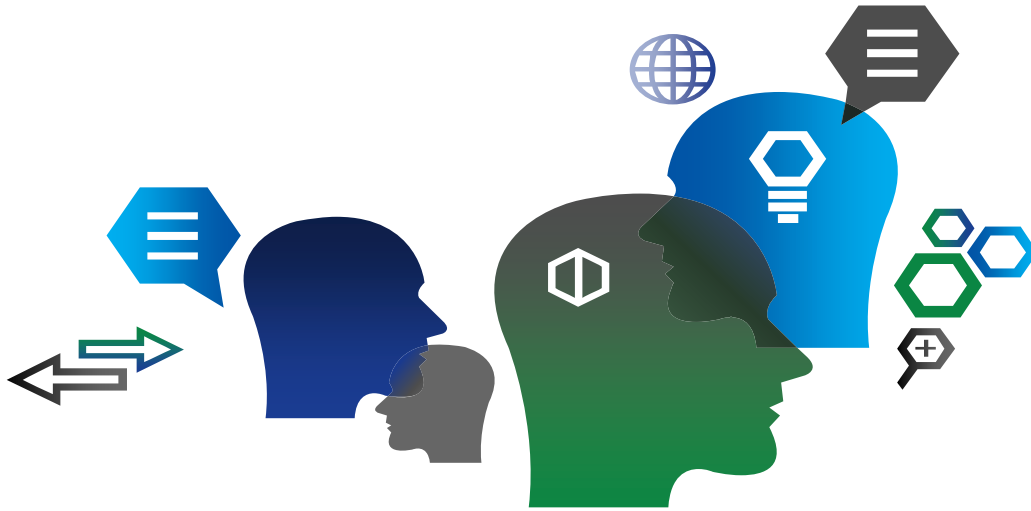


Centre de congrès WTC Grenoble

IWIPP 2022

2ND FLOOR : MAKALU (100 people in theater style) AND KILIMANDJARO (A buffet and 5 booths)





## THANK YOU FOR YOUR ATTENTION, PARTICIPATION, & INNOVATIVE THINKING

Without you, IWIPP wouldn't be a success.

Not only are we grateful for your participation, we want to hear from you about how we can improve in the future!

If you need anything throughout the conference or after it has come to an end, please feel free to reach out to the IWIPP Organizing Committee.

We hope that you fully enjoyed your time in Toulouse, and that you left with great knowledge to take back to your organization!

Sincerely, the 2022 IWIPP Leadership

[info@iwipp.org](mailto:info@iwipp.org)

# 2022 IWIPP